Migrating from OMAP3530 to AM35x

ABSTRACT

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This article describes hardware device considerations to migrate a design based on a TI OMAP3530 Application Processor to one based on a TI AM35x System-on-Chip (SoC) application processor. These two devices are based on similar ARM® CPU cores, features Neon & SGX graphics processor, and a mixture of memory and other peripherals useful in a system environment. Because this article describes the details for performing the migration from a TI OMAP3530 device to a TI AM35x device, familiarity with the OMAP3530 device and its documentation is assumed.

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